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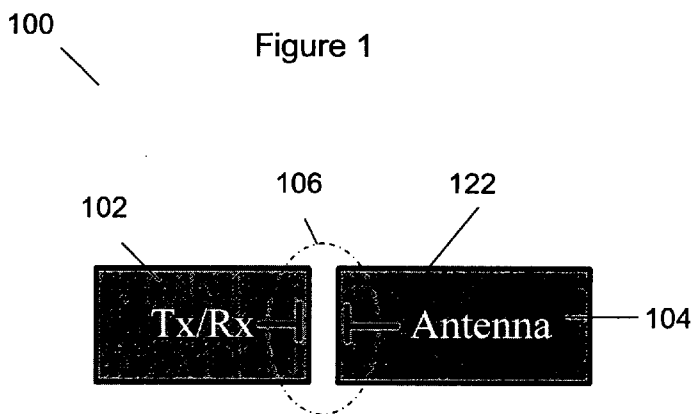
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(54) Title: AN INTEGRATED CIRCUIT STRUCTURE AND A METHOD OF FORMING THE SAME



(57) Abstract: An integrated circuit structure is disclosed. The integrated circuit structure includes a first package substrate including a radiating element, the radiating element having a radiating element connection extending from the radiating element. The integrated circuit structure further includes a first chip positioned adjacent to the radiating element connection, the first chip having a first chip connection on a surface of the first chip, wherein the first chip connection forms a capacitive coupling with the radiating element connection. A method of forming an integrated circuit structure is also disclosed.

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